

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

1. (Currently Amended) A method of forming a flip chip device, comprising:
 - providing a semiconductor die having a core area and a periphery area, the periphery area including an electrostatic discharge (ESD) structure, and the semiconductor die including at least one power conductor;
 - providing a substrate having a source of power;
 - locating a first connection circuit within the semiconductor die core area to couple power between the substrate and the semiconductor die power conductor;
 - electrically coupling the ESD structure to the first connection circuit; and
 - electrically coupling the first connection circuit to the substrate via a conductive bump.
2. (Original) The method of Claim 1 wherein the first connection circuit is a first under ball metallization (UBM).
3. (Amended) The method of Claim 2 further comprising:
 - locating a second UBM over the ESD structure; and
 - on the substrate, electrically coupling the first UBM to the second UBM.

4. (Currently Amended) The method of Claim 2 further comprising:
 - locating a second UBM over the ESD structure; and
 - on the semiconductor die, electrically coupling the first UBM to the second UBM.
5. (Original) The method of Claim 2 wherein the semiconductor die further comprises a redistribution layer; and
 - on the redistribution layer, electrically coupling the first UBM to the second UBM.
6. (Original) The method of Claim 2 wherein the semiconductor die includes a metallization side and an opposite side, the metallization side being electrically coupled to the substrate;
 - thermally coupling the opposite side of the semiconductor die to a heat sink.
7. (Original) The method of Claim 6 further comprising electrically coupling the substrate to a first surface of a package substrate via a plurality of bond wires.
8. (Original) The method of Claim 7 further including adhesively bonding the opposite side of the semiconductor die to the heat sink.